

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appln. No: 10/001,421
Applicant: Joseph M. Milewski et al.
Filed: November 2, 2001
Title: LOW TEMPERATURE SOLDER CHIP ATTACH STRUCTURE
TC/A.U.: 2811
Examiner: Hung K. Vu
Confirmation No.: 4204
Docket No.: END919970013US2

SUBMISSION OF FORMAL DRAWINGS

Mail Stop Issue Fee
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Responsive to the requirement dated September 24, 2004, for the submission of formal drawings in the above-identified application, formal drawings are submitted herewith.

Respectfully submitted,

RatnerPrestia


Lawrence E. Ashery, Reg. No. 34,515
Attorney for Applicants

LEA/pb

Enclosure: (3) Sheets of Drawings

Dated: October 27, 2004

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The Assistant Commissioner for Patents is hereby authorized to charge payment to Deposit Account No. 09-0457 (IBM Corporation) of any fees associated with this communication.